

# **APPROVAL SHEET**

**CrossAir™ SMD Antenna series**  
**RoHS Compliance**

**PN: CA-C03**

**2.4 GHz ISM band antenna**

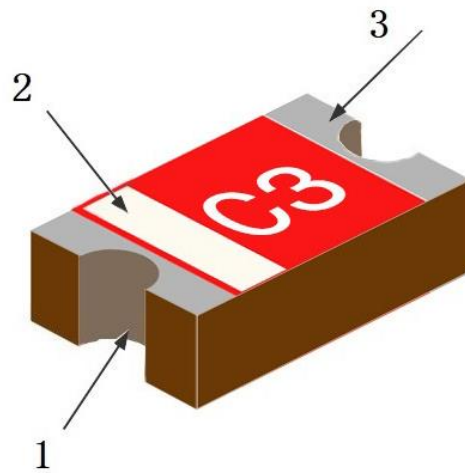
### FEATURES

1. Surface Mounted Devices (SMD) with a small dimension of 5.5 X 2.0 X 1.0 mm<sup>3</sup> meet miniaturization trend.
2. Low power loss and high antenna efficiency.
3. High stability in Temperature and Humidity Change.

### APPLICATIONS

1. 2.4GHz ISM band RF applications
2. Bluetooth, ZigBee, Wireless, HomeRF
3. WIFI (2.4G only)

### CONSTRUCTION



1、Antenna Feeding

2、Identification Mark

3、Soldering terminal

### DIMENSIONS

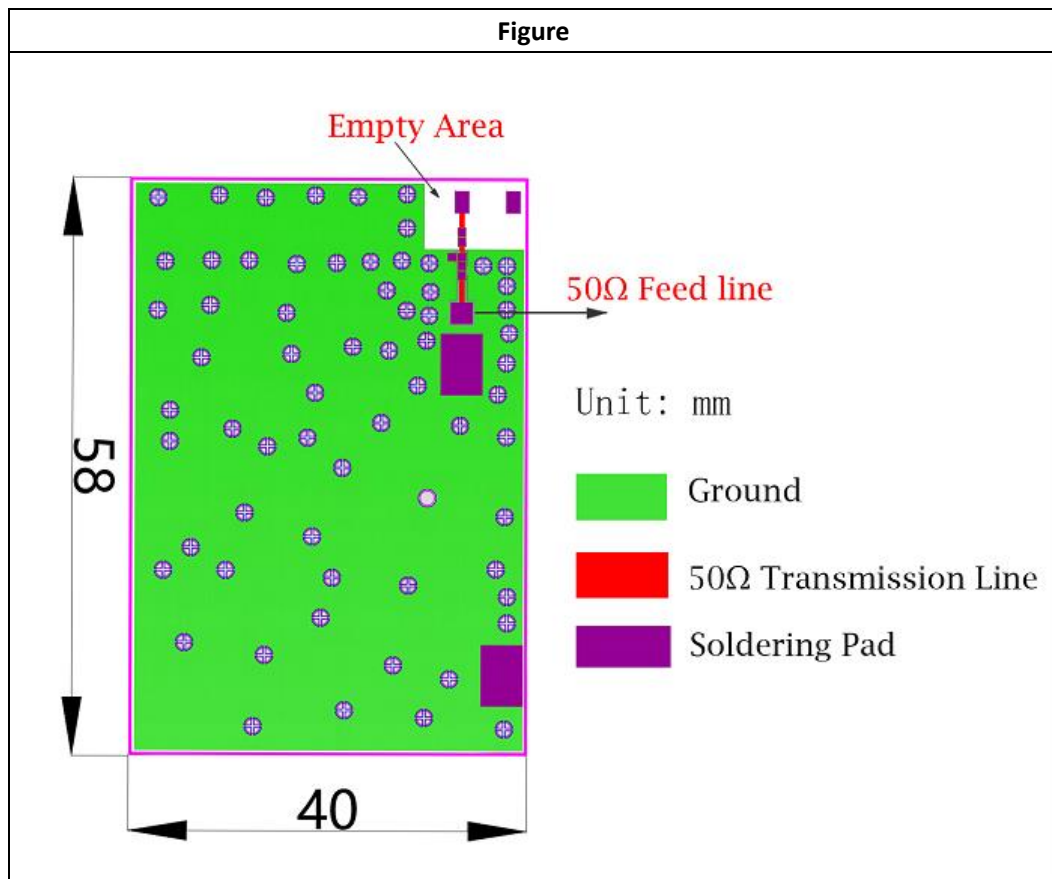
Figure	Symbol	Dimension(mm)
	<b>L</b>	<b>5.5±0.1</b>
	<b>w</b>	<b>2.0±0.1</b>
	<b>T</b>	<b>1.0±0.1</b>
	<b>a</b>	<b>0.5±0.1</b>

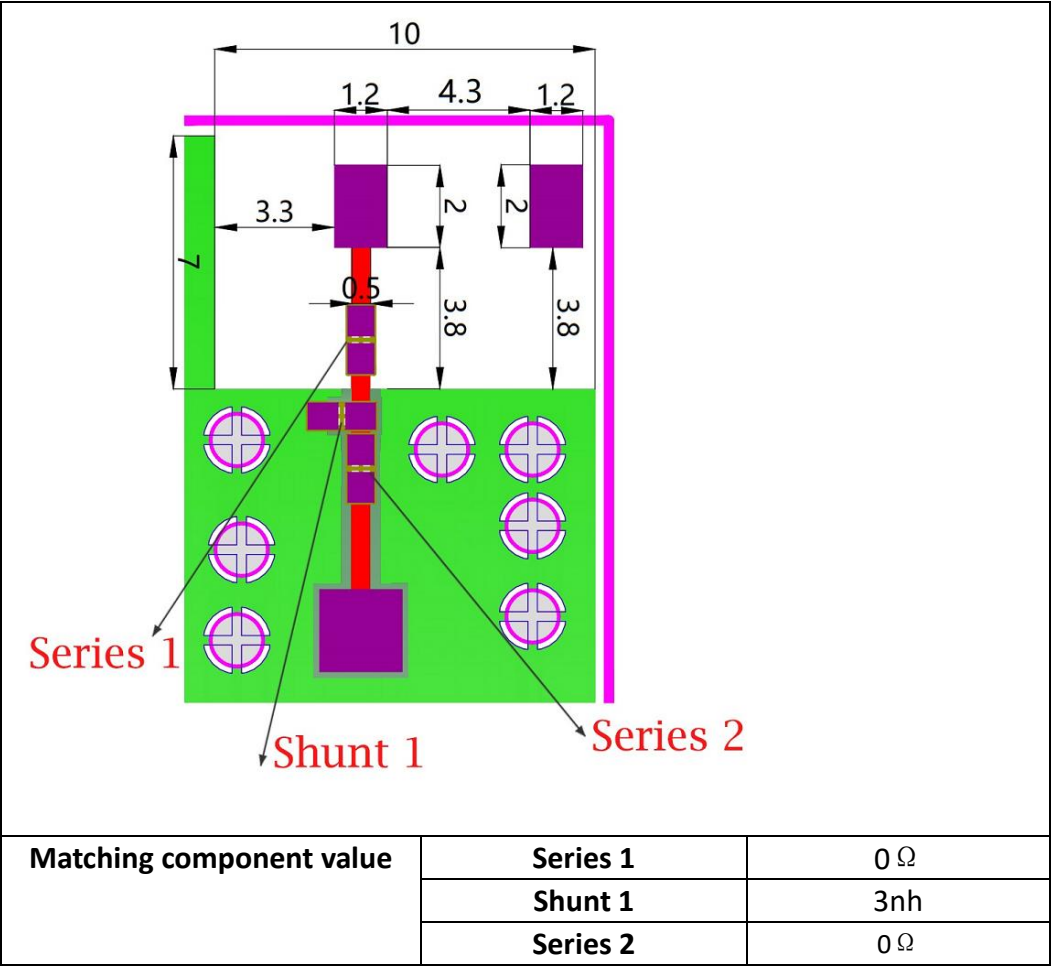
# ELECTRICAL CHARACTERISTICS

CA-C03	Specification
Working Frequency Range	2402-2480MHz
Fc(GHz)	2.7GHz
Band Width	>100MHz
Impedance	50 $\Omega$
Gain(dBi)	4.3 (peak)
VSWR	<2
Operation Temperature	-40℃~+95℃
Power Capacity	3W
Antenna type	Ceramic Antenna

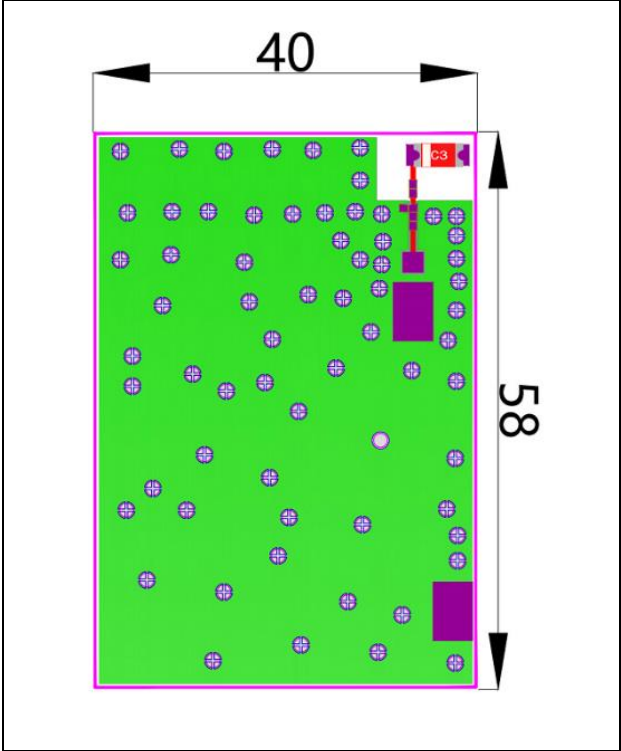
The working frequency need be adjusted to 2.45GHz with matching circuit.

## SOLDER LAND PATTERN DESIGN

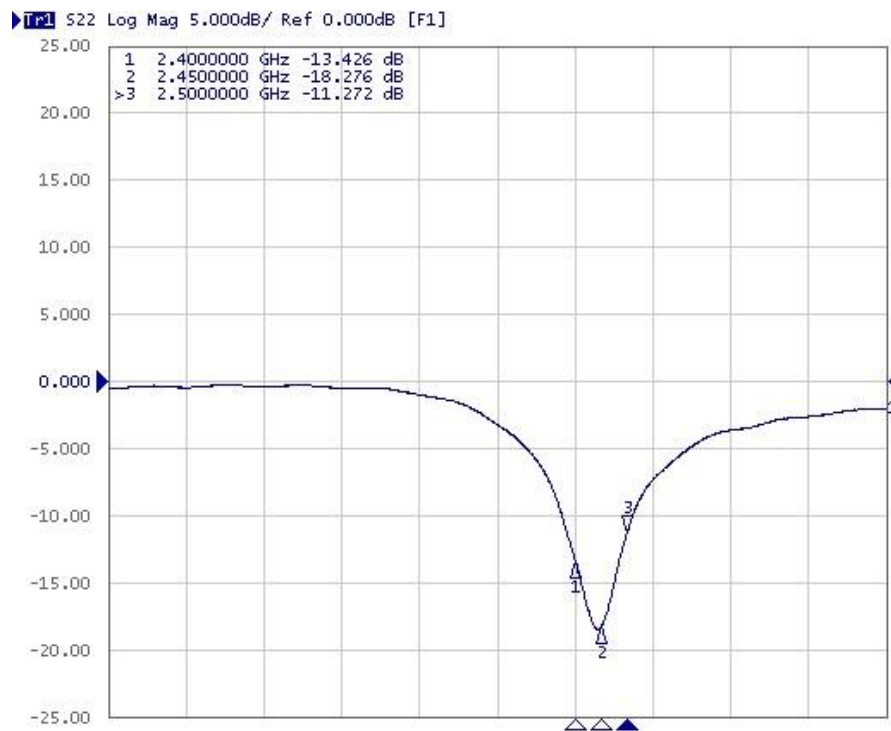




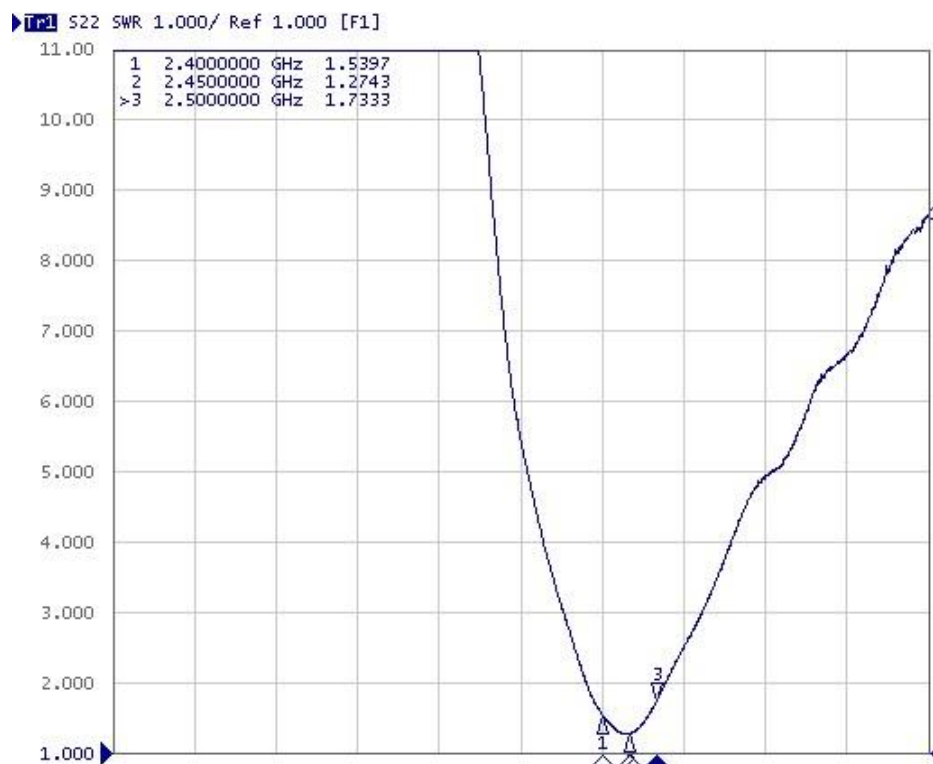
Antenna on Test Board (Thickness 1.0mm)



Antenna S11 on Test Board



Antenna VSWR on Test Board

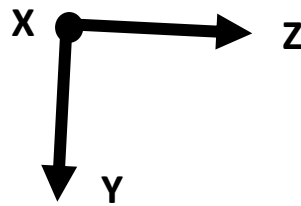
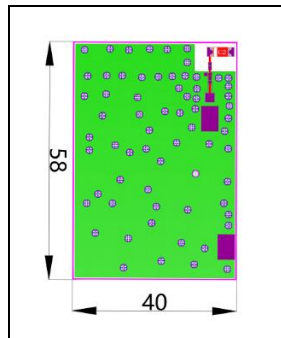


### Efficiency and RADIATION PATTERN

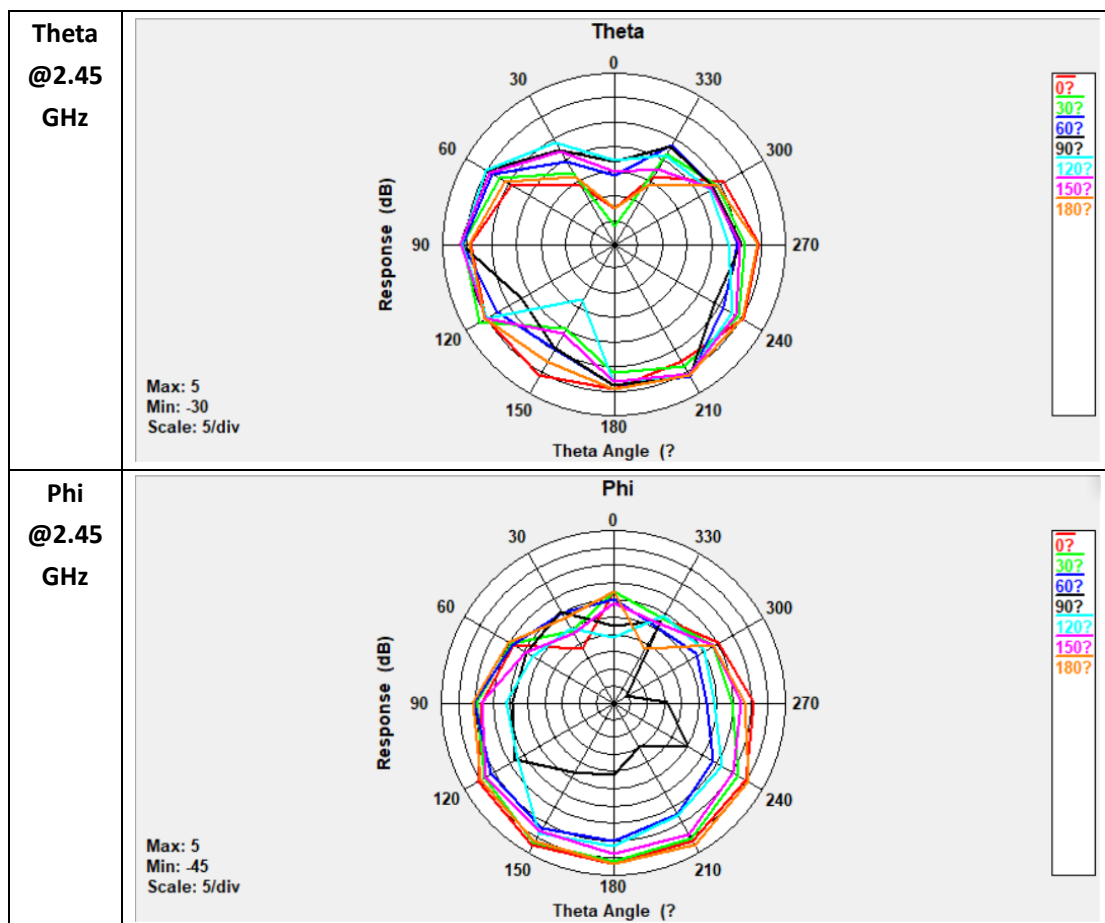
Efficiency, Radiation Pattern and Gain were dependent on measurement board design. The

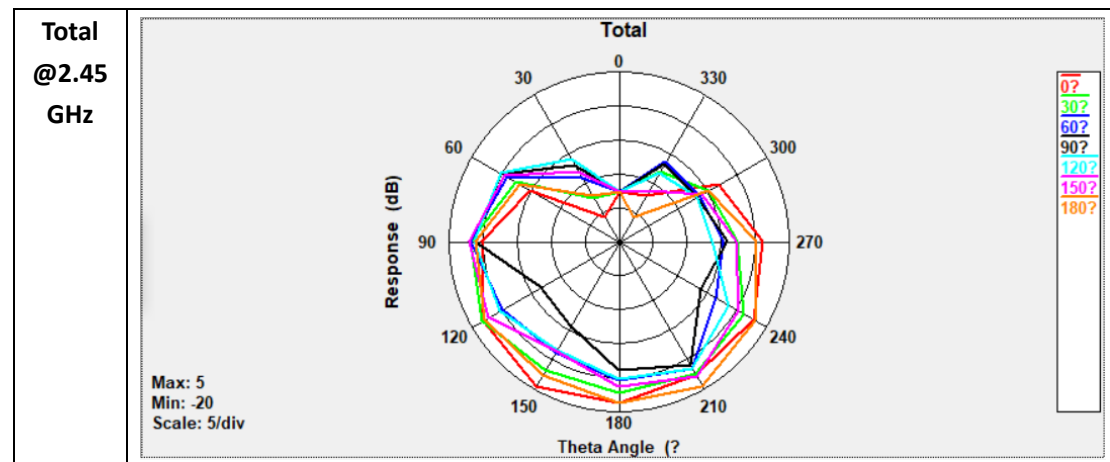
## Approval sheet

specification of CA-C03 antenna was measured based on the PCB size and installation position as shown in the below figure test board. The test results were tested in ETS 3D Chamber.



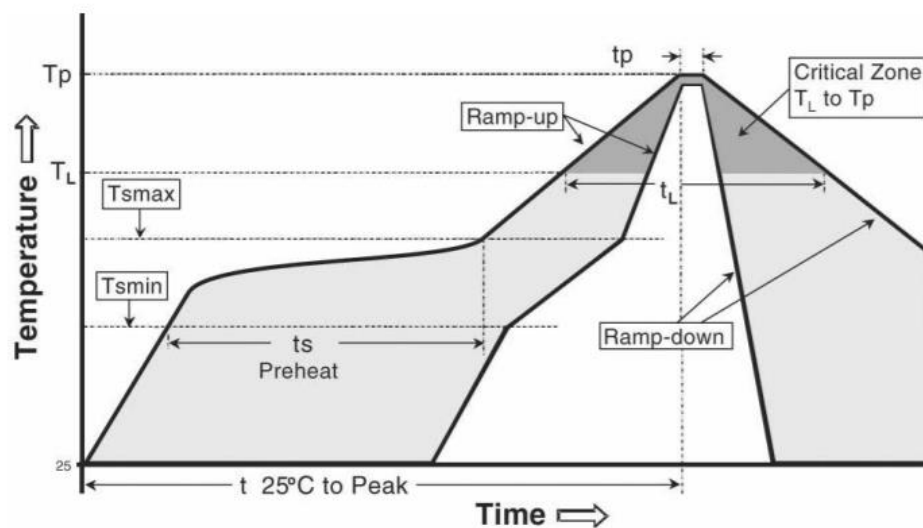
Gain and Efficiency	2.4G-2.5GHz
Peak Gain	4.3dBi
Average Gain across the band	4.1dBi
Gain Range across the band	3.9dBi~4.3dBi
Peak Efficiency	81.7%
Average Efficiency across the band	80.2%
Efficiency Range across the band	78.6%~81.7%





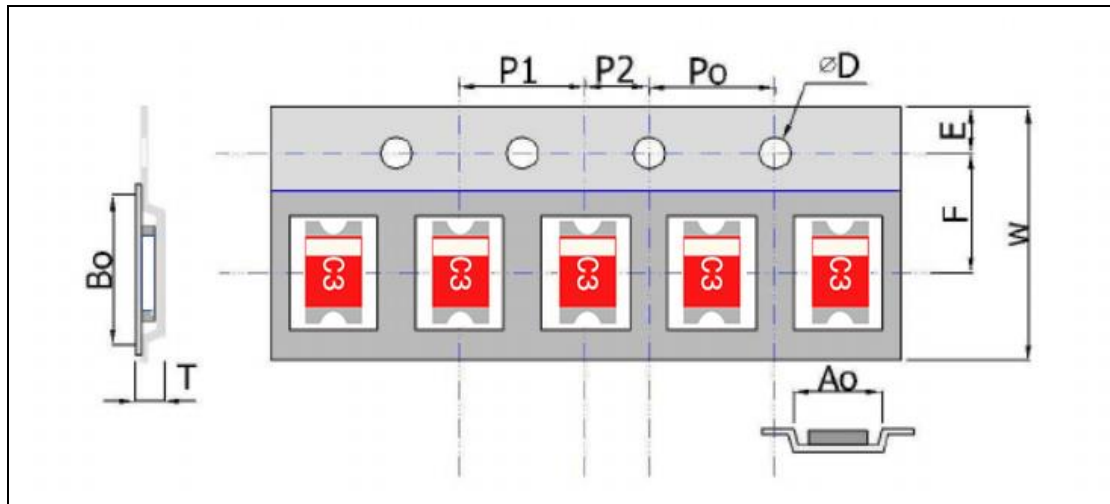
## SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage is as follows:



Phase	Profile features	Pb-Free assembly (SnAgCu)
<b>RAMP-UP</b>	Avg. Ramp-up Rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C / second (max.)
<b>PREHEAT</b>	<ul style="list-style-type: none"> <li>- Temperature Min (T<sub>smin</sub>)</li> <li>- Temperature Max (T<sub>smax</sub>)</li> <li>- Time (t<sub>smin</sub> to t<sub>smax</sub>)</li> </ul>	150 °C 200 °C 60-180 seconds
<b>REFLOW</b>	<ul style="list-style-type: none"> <li>- Temperature (T<sub>L</sub>)</li> <li>- Total Time above T<sub>L</sub> (t<sub>L</sub>)</li> </ul>	217 °C 60-150 seconds
<b>PEAK</b>	<ul style="list-style-type: none"> <li>- Temperature (T<sub>p</sub>)</li> <li>- Time (t<sub>p</sub>)</li> </ul>	260 °C 20-40 seconds
<b>RAMP-DOWN</b>	Rate	6 °C/second max
<b>Time from 25 °C to Peak Temperature</b>		8 minutes max

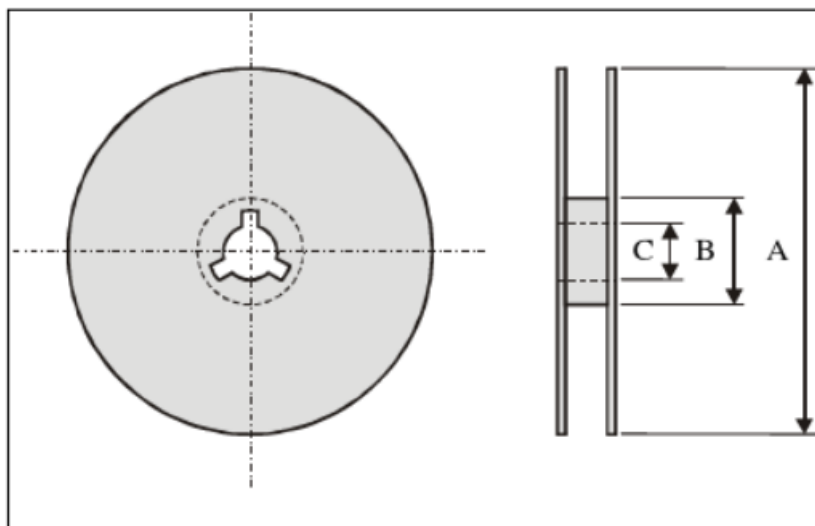
## PACKAGING



### Plastic Tape specification (unit:mm)

Index	Ao	Bo	$\Phi D$	T	W
Dimension (mm)	$3.0 \pm 0.1$	$6.0 \pm 0.1$	$1.55 \pm 0.05$	$1.2 \pm 0.1$	$11.8 \pm 0.1$
Index	E	F	Po	P1	P2
Dimension (mm)	$1.75 \pm 0.1$	$4.6 \pm 0.1$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.1$

### Reel dimensions



Index	A	B	C
Dimension(mm)	178	60	13.5

Typing Quantity: 3000 pieces per reel.

### CAUTION OF HANDLING

#### Storage environment condition

Products should be storage in the warehouse on the following conditions:



## Approval sheet

---

Temperature : -10℃~+40℃

Humidity : 30% to 70% relative humidity

Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.

Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.

Products should be storage under the airtight packaged condition.

Manufacturer: Beijing Ziroom Technology Co., Ltd

Address: Room 1105, Building 1, No. 17 Cangjingguan Hutong, Dongcheng District, Beijing